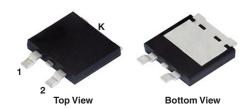


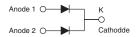
## Vishay General Semiconductor

# Dual High Voltage TMBS® (Trench MOS Barrier Schottky) Rectifier

### eSMP® Series



SMPD (TO-263AC)



PRIMARY CHARACTERISTICS			
I <sub>F(AV)</sub>	2 x 10.0 A		
V <sub>RRM</sub>	170 V		
I <sub>FSM</sub>	150 A		
V <sub>F</sub> at I <sub>F</sub> = 10.0 A (T <sub>A</sub> = 125 °C)	0.68 V		
T <sub>J</sub> max.	175 °C		
Package	SMPD (TO-263AC)		
Circuit configurations	Common cathode		

#### **FEATURES**



High efficiency operation

 Meets MSL level 1, J-STD-020, LF maximum peak of 260 °C

· Low forward voltage drop, low power losses

HALOGEN FREE

AEC-Q101 qualified available

· Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### TYPICAL APPLICATIONS

For use in high frequency DC/DC converters, switching power supplies, freewheeling diodes, OR-ing diode, and reverse battery protection.

#### **MECHANICAL DATA**

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: As marked

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER		SYMBOL	V20D170C	UNIT	
Device marking code			V20D170C		
Maximum repetitive peak reverse voltage		V <sub>RRM</sub>	170	V	
Maximum average forward rectified current (fig. 1)	per device	I <sub>F(AV)</sub>	20	۸	
	per diode		10	A	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load		I <sub>FSM</sub>	150	А	
Operating junction temperature range		T <sub>J</sub> <sup>(1)</sup>	-40 to +175	°C	
Storage temperature range		T <sub>STG</sub>	-55 to +175	°C	

#### Note

<sup>(1)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_{cl} < 1/R_{b,lA}$ 



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 5 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.75	-	- V
	I <sub>F</sub> = 10 A			0.83	0.9	
	I <sub>F</sub> = 5 A	T <sub>A</sub> = 125 °C		0.6	-	
	I <sub>F</sub> = 10 A			0.68	0.76	
Reverse current at rated $V_R$ per diode	V <sub>R</sub> = 140 V	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.001	-	mA
		T <sub>A</sub> = 125 °C		0.8	-	mA
	V 470 V	T <sub>A</sub> = 25 °C		-	0.15	mA
	V <sub>R</sub> = 170 V	T <sub>A</sub> = 125 °C		1.5	5	mA
Typical junction capacitance	4.0 V, 1 MHz		CJ	520	-	pF

#### **Notes**

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL V20D170C		UNIT	
Typical thermal resistance per device	R <sub>0</sub> JC (1)	1.5	°C/W	
rypical thermal resistance per device	R <sub>0</sub> JA (2)(3)	58	C/VV	

#### **Notes**

- (1) Mounted on infinite heatsink
- $^{(2)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$  junction-to-mount
- (3) Free air, without heatsink

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
V20D170C-M3/I	0.55	I	2000/reel	13" diameter plastic tape and reel		
V20D170CHM3/I (1)	0.55	I	2000/reel	13" diameter plastic tape and reel		

#### Note

(1) AEC-Q101 qualified

### **RATINGS AND CHARACTERISTICS CURVES** (T<sub>A</sub> = 25 °C unless otherwise noted)

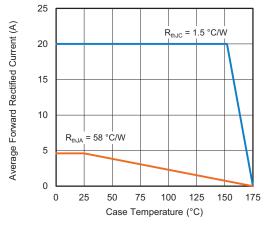


Fig. 1 - Forward Current Derating Curve

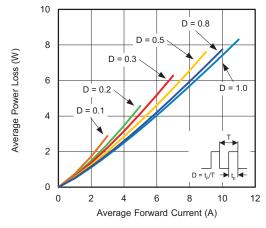


Fig. 2 - Forward Power Loss Characteristics



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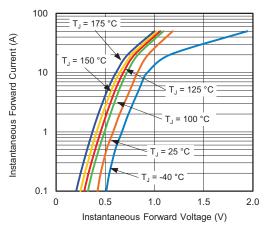


Fig. 3 - Typical Instantaneous Forward Characteristics

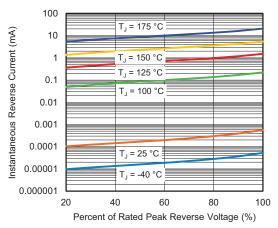


Fig. 4 - Typical Reverse Characteristics

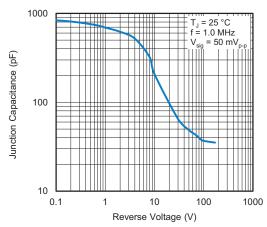


Fig. 5 - Typical Junction Capacitance

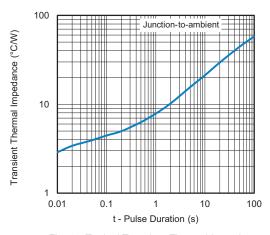


Fig. 6 - Typical Transient Thermal Impedance

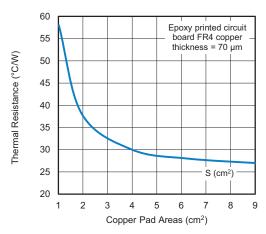
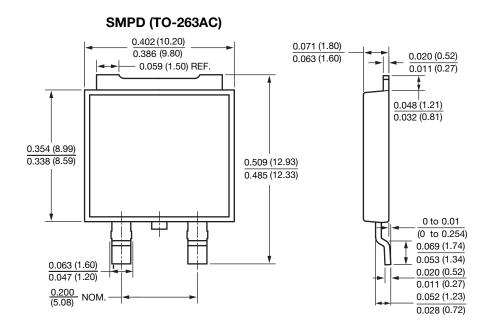


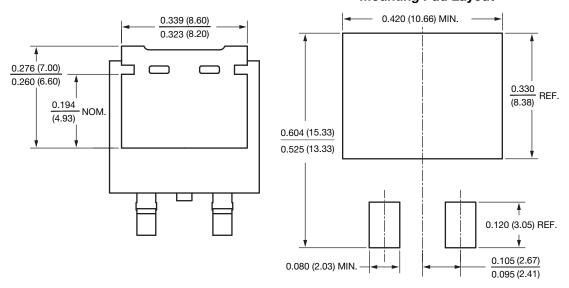
Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas

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### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)



### **Mounting Pad Layout**





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